

EN995141V



PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appn. No: 09/342,584
Applicant: Bernd K. Appelt et al.
Filed: June 29, 1999
Title: PRINTED CIRCUIT BOARDS FOR ELECTRONIC DEVICE PACKAGES HAVING
GLASS FREE NON-CONDUCTIVE LAYERS AND METHOD OF FORMING SAME
TC/A.U.: 2827
Examiner: Jose H. Alcala

SUBMISSION OF FORMAL DRAWINGS

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Responsive to the requirement dated April 15, 2004, for the submission of formal drawings in the above-identified application, formal drawings are submitted herewith.

Respectfully submitted,

RatnerPrestia

Daniel N. Calder

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Kevin R. Casey, Reg. No. 32,117
Attorneys for Applicants

DNC/pb

Enclosure: (3) Sheets of Formal Drawings

Dated: May 18, 2004

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The Assistant Commissioner for Patents is hereby
authorized to charge payment to Deposit Account
No. 09-0457 (IBM Corporation) of any fees
associated with this communication.